designating the United States of America, disclosed in the prior United States or PC	Filing Date (MC)  C. 120 of any United States a listed below and, insofar as the CT international application in ation which is material to pate	Annth/Day/Year)  Application(s), or 365(c) of any PCT international e subject matter of each of the claims of this application the manner provided by the first paragraph of 35 U ent ability as defined in 37 CFR 1.56 which became	ation is not
Application Number(s):  hereby claim the benefit under 35 U.S.C designating the United States of America, disclosed in the prior United States or PC	Filing Date (MC)  C. 120 of any United States a listed below and, insofar as the CT international application in	Annth/Day/Year)  application(s), or 365(c) of any PCT international e subject matter of each of the claims of this application the manner provided by the first paragraph of 35 U	application ation is not .S.C. 112, I
Application Number(s):  hereby claim the benefit under 35 U.S.C designating the United States of America,	Filing Date (MC)  C. 120 of any United States a listed below and, insofar as the	Month/Day/Year)  application(s), or 365(c) of any PCT international e subject matter of each of the claims of this application.	application ation is not
Application Number(s):  hereby claim the benefit under 35 U.S.C.	Filing Date (M	Annth/Day/Year) application(s), or 365(c) of any PCT international	application
Application Number(s):	Filing Date (M	Ionth/Day/Year)	
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I hereby claim the benefit under 35 U.S.C.	. 119(e) of any United States p		
		rovisional application(s) listed below.	
2003-0052036	Korea	July 28, 2003	
2003-0036894	Korea	June 9, 2003	
Prior Foreign Application(s): Number	Country	Foreign Filing Date Month/Day/Year	
certificate, or 365(a) of any PCT international listed below and have also identified below	onal application which designat w, by checking the box, any for	365 (b) of any foreign application(s) for patent or ed at least one country other than the United States eign application for patent or inventor's efore that of the application on which priority is claim	of America
		be material to patent ability in accordance with Title	le 37, Code
		pove identified specification, including the claims,	
[X] is attached hereto [ ] was filed on was amended on	(if applicable)	as Application Serial No.	and
DISSIPATING STRUCTURE F	OR MOBILE DEVICE,	the specification of which	
names are listed below) of the subject mat	tter claimed and for which a pa	tent is sought on the invention entitled: HEAT	
I believe I am the original, first and sole in	nventor (if only one name is lis	ted below) or an original, first and joint inventor (if p	olural
My residence, post office and citizenship a	are as stated below next to my	name,	
	are that:		
As a below named inventor, I hereby decl			
	RATION AND PO	WER OF ATTORNEY	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vazquez, Registration No. 38,647; and Michael J. Cornelison, Registration No. 40,395; and Carol L. Druzbick, Registration No. 40,287, all of

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with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and all future correspondence should be addressed to them.			
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